

WHAT IS CLAIMED IS:

1. A dicing/die-bonding film comprising a pressure-sensitive adhesive layer (2) on a supporting base material (1) and a die-bonding adhesive layer (3) on the pressure-sensitive adhesive layer (2),

wherein a releasability in an interface between the pressure-sensitive adhesive layer (2) and the die-bonding adhesive layer (3) is different between an interface (A) corresponding to a work-attaching region (3a) in the die-bonding adhesive layer (3) and an interface (B) corresponding to a part or a whole of the other region (3b),

and the releasability of the interface (A) is higher than the releasability of the interface (B).

2. The dicing/die-bonding film according to claim 1, wherein an adhesion of the pressure-sensitive adhesive layer (2) to the die-bonding adhesive layer (3) is different between a region (2a) corresponding to the work-attaching region (3a) in the die-bonding adhesive layer (3) and a region (2b) corresponding to a part or the whole of the other region (3b), and satisfies the relationship:

the adhesion of the pressure-sensitive adhesive layer (2a) is lower than the adhesion of the pressure-sensitive adhesive layer (2b).

3. The dicing/die-bonding film according to claim 1, wherein an adhesion of the work-attaching region (3a) in the die-bonding adhesive layer (3) to a work and to the pressure-sensitive adhesive

layer (2a) satisfies the relationship:

the adhesion to the work is higher than the adhesion to the pressure-sensitive adhesive layer (2a).

4. The dicing/die-bonding film according to claim 1, wherein
5 the part of the region (3b) other than the work-attaching region (3a) in the die-bonding adhesive layer (3) is a dicing ring-attaching region (3b').

5. The dicing/die-bonding film according to claim 4, wherein
an adhesion of the dicing ring-attaching region (3b') in the
10 die-bonding adhesive layer (3) to the dicing ring and to the pressure-sensitive adhesive layer (2b') satisfies the relationship:

the adhesion to the dicing ring is lower than the adhesion to the pressure-sensitive adhesive layer (2b').

6. A dicing/die-bonding film comprising a pressure-sensitive
15 adhesive layer (2) on a supporting base material (1) and a die-bonding adhesive layer (3) on the pressure-sensitive adhesive layer (2),

wherein the die-bonding adhesive layer (3) is arranged as a work-attaching region (3a) on a part of the pressure-sensitive
20 adhesive layer (2), and

a region (2a) corresponding to the work-attaching region (3a) in the pressure-sensitive adhesive layer (2) and the other region (2b) are different in adhesion and satisfy the relationship:

the adhesion of the pressure-sensitive adhesive layer (2a) is
25 lower than the adhesion of the pressure-sensitive adhesive layer

(2b).

7. The dicing/die-bonding film according to claim 6, wherein an adhesion of the work-attaching region (3a) to the work and to the pressure-sensitive adhesive layer (2a) satisfies the relationship:

5 the adhesion to the work is higher than the adhesion to the pressure-sensitive adhesive layer (2a).

8. The dicing/die-bonding film according to claim 1, wherein the pressure-sensitive adhesive layer (2) is formed from a radiation-curing pressure-sensitive adhesive, and the
10 pressure-sensitive adhesive layer (2a) corresponding to the work-attaching region (3a) is irradiated with radiations.

9. The dicing/die-bonding film according to claim 6, wherein the pressure-sensitive adhesive layer (2) is formed from a radiation-curing pressure-sensitive adhesive, and the
15 pressure-sensitive adhesive layer (2a) corresponding to the work-attaching region (3a) is irradiated with radiations.

10. A method of fixing a chipped work, comprising the steps of:

20 pressing a work onto a die-bonding adhesive layer (3a) in the dicing/die-bonding film described in any one of claims 1 to 9,

 dicing the work into chips,

 releasing the chipped work together with the die-bonding adhesive layer (3a) from the pressure-sensitive adhesive layer (2a),
and

25 fixing the chipped work to a semiconductor element via the

die-bonding adhesive layer (3a).

11. A semiconductor device comprising a chipped work fixed onto a semiconductor element via the die-bonding adhesive (3a) by the method of fixing a chipped work as described in claim 10.